

Please amend the entire paragraph beginning at page 14, line 13, as shown in the following Clean Version, a Marked-Up Version of which is attached to this Amendment:

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--Referring to Fig. 20, the same method in accordance with the present invention may be used make another type coplanar waveguide of a microwave circuit of a printed circuit board. After the metallic ground layer 51 is mounted on the bottom side of the dielectric substrate 52, a high dielectric value material 54 may be coated or printed on the metallic ground layer 51. At this time, multiple circular pads 55 are formed in the high dielectric value material 54, thereby exposing the metallic ground layer 51 not coated or printed with the high dielectric value material 54. Then, the high dielectric value material 54 is covered with metallic paste or high conductive material that may be filled into the circular pads 55, thereby forming a planar jumper layer 55 that is connected to the metallic ground layer 51 through the circular pads 55.--

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IN THE CLAIMS

Please cancel claims ~~2~~ and ~~6~~ without prejudice.

Please amend claims 1, 4, 5 and 7-14 as shown in the following Clean Version, a Marked-Up Version of which is attached to this Amendment:

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--1. (amended) A method for making a printed circuit board having jumper lines, comprising the steps of:

a) making a printed circuit board;

b) coating or printing a high dielectric value material on the printed circuit board to form an isolation layer;

c) forming multiple pads in the isolation layer of the high dielectric value material, thereby exposing part of the printed circuit board not covered by the high dielectric value material; and

d) coating or printing a high conductive material on the isolation layer of the high dielectric value material to connect the multiple pads, thereby forming a planar jumper layer that is connected to the printed circuit board through the pads.--

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--4. (amended) A method for making a printed circuit board having jumper lines, comprising the steps of:

a) determining a pre-estimated value of an effective dielectric constant;

b) determining a shortened size of a microwave circuit according to the pre-estimated value of the effective dielectric constant and a used working frequency;

c) providing a dielectric substrate that can increase the effective dielectric constant to the pre-estimated value;

d) making the microwave circuit with a shortened size on the dielectric substrate;

e) coating or printing an isolation layer on the microwave circuit;

f) forming multiple pads in the isolation layer, thereby exposing part of the microwave circuit not covered by the isolation layer; and

g) coating or printing a high conductive material on the isolation layer to connect the multiple pads, thereby forming a planar jumper layer that is connected to the microwave circuit through the pads.--

--5. (amended) A printed circuit board having jumper lines, comprising: a line layer, an isolation layer made of a dielectric material coated on the line layer, multiple pads formed in the isolation layer, thereby exposing part of the line layer not covered by the isolation layer, and a high conductive material coated on the isolation layer to connect the multiple pads, thereby forming a planar jumper layer that is connected to the line layer through the pads; wherein:

the printed circuit board is overlapped with other circuit substrates, thereby forming a multi-layer printed circuit board.--

--7 (amended) A printed circuit board having jumper lines, comprising: a dielectric substrate, a metallic ground layer mounted on a first side of the dielectric substrate, and a line layer mounted on a second side of the dielectric substrate, an isolation layer made of a high dielectric value material coated on the line layer, multiple pads formed in the isolation layer, thereby exposing part of the line layer not covered by the isolation layer, and a high conductive material coated on the isolation layer to connect the multiple pads, thereby forming a planar jumper layer that is connected to the line layer through the pads.--

--8. (amended) The printed circuit board having jumper lines in accordance with claim 7, wherein the printed circuit board is overlapped with other circuit substrates, thereby forming a multi-layer printed circuit board.--

--9. (amended) A printed circuit board having jumper lines, comprising: a dielectric substrate, a metallic ground layer mounted on one side of the dielectric substrate, an isolation layer made of a high dielectric value material coated on the metallic ground layer, multiple pads formed in the isolation layer, thereby exposing part of the metallic ground layer not covered by the isolation layer, and a high conductive material coated on the isolation layer to connect the multiple pads, thereby forming a planar jumper layer that is connected to the metallic ground layer through the pads.--

--10. (amended) The printed circuit board having jumper lines in accordance with claim 9, wherein the printed circuit board is overlapped with other circuit substrates, thereby forming a multi-layer printed circuit board.--

--11. (amended) A printed circuit board having jumper lines, comprising: a dielectric substrate made of a high dielectric value material, a metallic ground layer mounted on a first side of the dielectric substrate, a line layer mounted on a second side of the dielectric substrate, an isolation layer coated on the line layer, multiple pads formed in the isolation layer, thereby exposing part of the line layer not covered by the isolation layer, and a high conductive material coated on the isolation layer to connect the multiple pads, thereby forming a planar jumper layer that is connected to the line layer through the pads.--

--12. (amended) The printed circuit board having jumper lines in accordance with claim 11, wherein the printed circuit board is overlapped with other circuit substrates, thereby forming a multi-layer printed circuit board.--

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--13. (amended) A printed circuit board having jumper lines, comprising: a dielectric substrate made of a high dielectric value material, a metallic ground layer mounted on one side of the dielectric substrate, an isolation layer coated on the metallic ground layer, multiple pads formed in the isolation layer, thereby exposing part of the metallic ground layer not covered by the isolation layer, and a high conductive material coated on the isolation layer to connect the multiple pads, thereby forming a planar jumper layer that is connected to the metallic ground layer through the pads.--

--14. (amended) The printed circuit board having jumper lines in accordance with claim 13, wherein the printed circuit board is overlapped with other circuit substrates, thereby forming a multi-layer printed circuit board.--

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